

REMARKS

Summary of the Office Action

Claims 88-124 are pending.

Claims 88-92, 95-118, 120, 122, and 123 were rejected under 35 U.S.C. § 102(b) as being anticipated by Wojnarowski U.S. Patent No. 5,324,687 (hereinafter "Wojnarowski").

Claims 93, 94, 119, 121, and 124 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Wojnarowski.

Summary of Applicant's Amendments

Applicant has added claims 125-145 in order to more particularly point out and distinctly claim the subject matter that applicant regards as the invention.

Applicant has amended claims 88, 97-101 and 123-124 to more particularly define the claimed invention.

Applicant's Reply to the Rejection Under 35 U.S.C. § 102(b)

Claims 88-92, 95-118, 120, 122, and 123 were rejected under 35 U.S.C. § 102(b) as being anticipated by Wojnarowski.

Applicant's specification discusses a stack of monolithic substrates. Any one of these monolithic substrates can be processed and included in the stack as a substantially flexible substrate.

Wojnarowski discusses two dice that may be provided in a die carrier layer that, in turn, is provided on a single, temporary holding layer. The holding layer is either a metal, polymer, or alumina (See Wojnarowski, col. 5, lines 7-9). The die carrier layer is a removable (or dissolvable) material that is capable of being separated from dice 12 and 14 (See Wojnarowski, col. 4, lines 39-42).

The Examiner stated that Wojnarowski discusses "at least one of a plurality of substrates [that] is a substantially flexible substrate (FIG. 7; col. 8; lines 10-38)." (Office Action, page 2)

Claim 88

Applicant's invention, as defined by amended claim 88, includes a plurality of monolithic substrates stacked in layers, wherein no more than one substrate is provided in any layer. Wojnarowski does not suggest a stack of monolithic substrates - let alone a stack that includes a substantially flexible monolithic substrate.

For at least this reason, applicant's respectfully request that the Examiner's rejections of claim 88, and any claims dependent therefrom, in view of Wojnarowski be withdrawn.

Claim 97

Applicant's invention, as defined by amended claim 97, includes a substantially flexible monolithic substrate bonded to the surface of another substrate, where no other substrates are bonded to that surface. Wojnarowski does not suggest bonding a substantially flexible monolithic substrate to the surface of another substrate, where no other substrates are bonded to that surface.

For at least this reason, applicant's respectfully request that the Examiner's rejections of claim 97, and any claims dependent therefrom, in view of Wojnarowski be withdrawn.

Claim 101

Applicant's invention, as defined by amended claim 101, includes a plurality of substrates that are bonded with thermal diffusion bonding, where at least one of these substrates is a substantially flexible monolithic substrate.

Wojnarowski does not suggest a plurality of substrates bonded with thermal diffusion bonding - let alone thermal diffusion bonding between substrates where one of the substrates is a substantially flexible monolithic substrate.

Additionally, the Examiner stated that Wojnarowski also shows "complimentary patterns of a material bondable using thermal diffusion bonding (FIG. 3; col. 5, lines 36-66)" (Office Action, page 4). Wojnarowski, however, does not show or suggest thermal diffusion bonding. Instead, Wojnarowski discusses only an adhesive. No technique of thermal diffusion bonding is discussed by Wojnarowski.

For at least these reasons, applicant's respectfully request that the Examiner's rejections of claim 101, and any claims dependent therefrom, in view of Wojnarowski be withdrawn.

Applicant's Reply to the Rejection Under 35 U.S.C. § 103(a)

Claims 93, 94, 119, 121, and 124 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Wojnarowski.

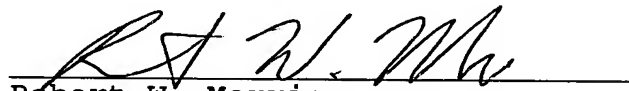
As shown above, claims 88, 97, and 101 are allowable. Accordingly, claims 93, 94, 119, 121, and 124 are

allowable because each of claims 93, 94, 119, 121, and 124 depend from one of claims 88, 97, or 101.

Conclusion

Applicant respectfully submits that this application, including claims 88-145, is in condition for allowance.

Respectfully submitted,

A handwritten signature in cursive script, appearing to read "R. W. Morris", is written over a horizontal line.

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